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(54) Title: WAFER SIGNATURE LOCAL MAXIMA VIA CLUSTERING FOR METROLOGY GUIDED INSPECTION

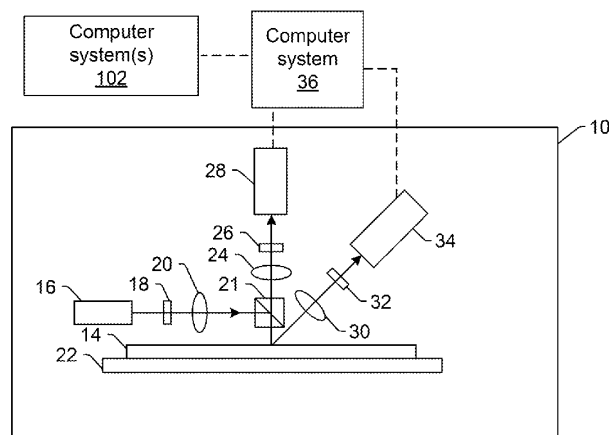


Fig. 1

(57) Abstract: Methods and systems for generating information for use in setting up a process performed on a specimen are provided. One method includes clustering dies on a specimen based on colors assigned to the dies responsive to predicted defect densities in the dies determined from measurements performed on the specimen thereby generating initial die clusters. The method also includes analyzing the initial die clusters in location space to determine if any of the initial die clusters contain two or more die clusters. In addition, the method includes designating the initial die clusters that do not contain two or more die clusters and the two or more die clusters contained in any of the initial die clusters as the final die clusters. The method further includes storing information for the final die clusters for use in setting up a process performed on the specimen.

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